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2013年12月

## FGH40T65SPD

## 650 V、 40 A 场截止沟道 IGBT

#### 特性

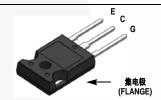
- 最大结温: T」=175°C
- 正温度系数,易于并联运行
- 低饱和电压: V<sub>CE(sat)</sub>=1.85 V (典型值) @ I<sub>C</sub>=40 A
- 高输入阻抗
- 快速开关
- 紧密的参数分布
- 符合 RoHS 标准
- 短路耐用性 > 5 µs @ 25°C

### 概述

飞兆半导体的场截止第 3 代 IGBT 新系列采用新型场截止 IGBT 技术,为光伏逆变器、 UPS、焊机、电信、 ESS 和 PFC 等低导 通和开关损耗至关重要的应用提供最佳性能。

#### 应用

• 光伏逆变器、 UPS、焊机、 PFC、电信、 ESS





#### 绝对最大额定值

符号	说	明	FGH40T65SPD_F155	单位
V <sub>CES</sub>	集电极 - 发射极之间电压		650	V
$V_{GES}$	栅极一发射极间电压		± 20	V
	瞬态栅极一发射极间电压		± 30	V
I <sub>C</sub>	集电极电流	@ T <sub>C</sub> = 25°C	80	Α
10	集电极电流	@ T <sub>C</sub> = 100°C	40	Α
I <sub>CM</sub>	集电极脉冲电流		120	Α
I <sub>F</sub>	二极管正向电流	@ T <sub>C</sub> = 25°C	40	Α
'F	二极管正向电流	@ T <sub>C</sub> = 100°C	20	Α
I <sub>FM</sub>	二极管最大正向脉冲电流		120	Α
P <sub>D</sub>	最大功耗	@ T <sub>C</sub> = 25°C	267	W
. 0	最大功耗	@ T <sub>C</sub> = 100°C	134	W
SCWT	短路耐受时间 @ T <sub>C</sub> = 25°C		5	μS
TJ	工作结温		-55 至 +175	°C
T <sub>stg</sub>	存储温度范围		-55 至 +175	°C
TL	用于焊接的最大引脚温度,距离外壳 1/8",持续 5 秒		300	°C

**注意:** 1: 重复额定值: 脉宽受最大结温限制

#### 热性能

符号	参数	典型值	最大值	单位
$R_{\theta JC}(IGBT)$	结点 - 壳体的热阻	-	0.56	°C/W
R <sub>θJC</sub> (二极管)	结点 - 壳体的热阻	-	1.71	°C/W
$R_{\theta JA}$	结至环境热阻	-	40	°C/W

1

## 封装标识与定购信息

器件标识	器件	封装	卷尺寸	带宽	每卷管数量
FGH40T65SPD	FGH40T65SPD_F155	TO-247 G03	-	-	30ea

## **IGBT 的电气特性** T<sub>C</sub> = 25°C 除非另有说明

符号	参数	测试条件	最小值	典型值	最大值	单位
关断特性						
BV <sub>CES</sub>	集电极 - 发射极击穿电压	$V_{GE} = 0 \text{ V}, I_C = 1 \text{ mA}$	650	-	-	V
DBV <sub>CES</sub>	击穿温度系数电压	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	-	0.6	-	V/°C
I <sub>CES</sub>	集电极切断电流	V <sub>CE</sub> = V <sub>CES</sub> , V <sub>GE</sub> = 0 V	-	-	250	μΑ
$I_{GES}$	G-E 漏电流	$V_{GE} = V_{GES}$ , $V_{CE} = 0 V$	-	-	± 400	nA
导通特性						
V <sub>GE(th)</sub>	G-E 阈值电压	$I_C$ = 40 mA, $V_{CE}$ = $V_{GE}$	4	5.5	7.5	V
		I <sub>C</sub> = 40 A, V <sub>GE</sub> = 15 V	-	1.85	2.4	V
V <sub>CE(sat)</sub>	集电极 - 发射极间饱和电压	I <sub>C</sub> = 40 A. V <sub>GE</sub> = 15 V, T <sub>C</sub> = 175°C	-	2.51	-	V
动态特性						
C <sub>ies</sub>	输入电容		-	1370	-	pF
C <sub>oes</sub>	输出电容	$V_{CE} = 30 \text{ V},  V_{GE} = 0 \text{ V},$ f = 1 MHz	-	94	-	pF
C <sub>res</sub>	反向传输电容	T = 1 1VII 12	-	16	-	pF
开关特性						
T <sub>d(on)</sub>	导通延迟时间		-	16	-	ns
T <sub>r</sub>	上升时间		-	42	-	ns
T <sub>d(off)</sub>	关断延迟时间	$V_{CC} = 400 \text{ V}, I_{C} = 40 \text{ A},$ $R_{G} = 6 \Omega, V_{GE} = 15 \text{ V},$	-	37	-	ns
T <sub>f</sub>	下降时间		-	11	-	ns
E <sub>on</sub>	导通开关损耗	————————————————————————————————————	- /	1.16	-	mJ
E <sub>off</sub>	关断开关损耗		-	0.28	-	mJ
E <sub>ts</sub>	总开关损耗		-	1.44	-	mJ
T <sub>d(on)</sub>	导通延迟时间		-	14	- )/	ns
T <sub>r</sub>	上升时间		-	49	/-	ns
T <sub>d(off)</sub>	关断延迟时间	V <sub>CC</sub> = 400 V, I <sub>C</sub> = 40 A,	-	38	/ -	ns
T <sub>f</sub>	下降时间	$R_G = 6 \Omega$ , $V_{GE} = 15 V$ ,	-	18	- //	ns
E <sub>on</sub>	导通开关损耗	感性负载, T <sub>C</sub> =175°C	-	1.54	-	mJ
E <sub>off</sub>	关断开关损耗		-	0.52	-	mJ
E <sub>ts</sub>	总开关损耗		-	2.06	-	mJ
T <sub>SC</sub>	短路耐受时间	$V_{CC} = 400 \text{ V},  V_{GE} = 15 \text{ V},$ $R_G = 10 \Omega$	5	-	-	μs

## IGBT 电气特性 (接上页)

符号	参数	测试条件	最小值	典型值	最大值	单位
$Q_g$	总栅极电荷		-	35	-	nC
Q <sub>ge</sub>	栅极一发射极间电荷	$V_{CE} = 400 \text{ V}, I_{C} = 40 \text{ A},$ $V_{GE} = 15 \text{ V}$	-	11	-	nC
$Q_{gc}$	栅极一发射极间电荷	*GE 'V	-	12	-	nC

## 二极管电气特性 T<sub>C</sub> = 25°C 除非另有说明

符号	参数		测试条件		最小值	典型值	最大值	单位
V <sub>FM</sub>	二极管正向电压	I_ =	20 A	T <sub>C</sub> = 25°C	-	2.2	2.7	V
FINI	一版自正的毛压	.F		T <sub>C</sub> = 175°C	-	1.9	-	
E <sub>rec</sub>	反向恢复电能			T <sub>C</sub> = 175°C	-	76	-	μJ
T <sub>rr</sub>	二极管反向恢复时间		20 A, dI <sub>F</sub> /dt=200 A/µs	T <sub>C</sub> = 25°C	1	34	-	ns
		1 <sub>F</sub> = 2	F - 20 A, αιF/αι-200 Α/μδ	T <sub>C</sub> = 175°C	-	196	-	
Q <sub>rr</sub>	二极管反向恢复电荷			T <sub>C</sub> = 25°C	-	52	-	nC
~11	ᆛᄶᆸᄷᄓᄷᇰᅹᆒ			T <sub>C</sub> = 175°C	-	638	-	

#### 图 1. 典型输出特性

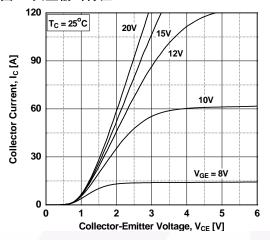


图 2. 典型输出特性

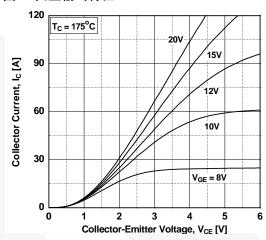


图 3. 典型饱和电压特性

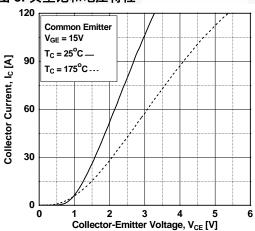


图 4. 饱和电压与壳温的关系 (可变电流强度下)

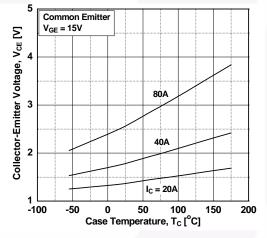


图 5. 饱和电压与 V<sub>GE 的关系</sub>

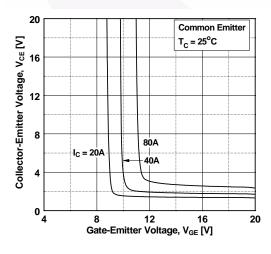
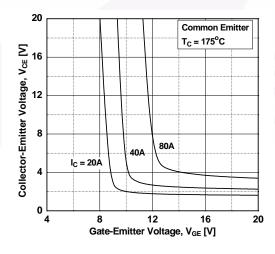
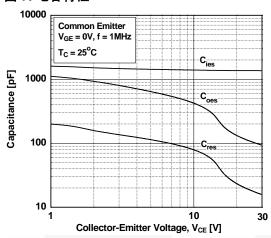


图 6. 饱和电压与 V<sub>GE</sub> 的关系



#### 图 7. 电容特性



#### 图 8. 栅极电荷特性

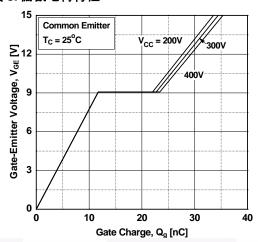


图 9. 导通特性与栅极电阻的关系

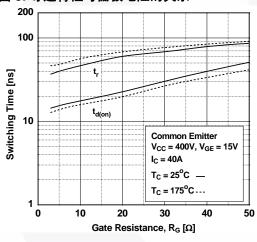


图 10. 关断特性与栅极电阻的关系

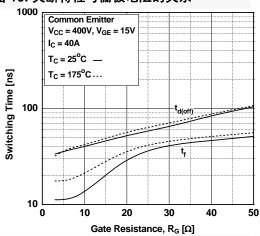
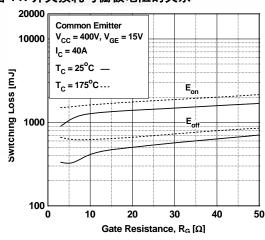


图 11. 开关损耗与栅极电阻的关系



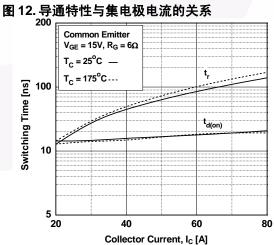


图 13. 关断特性与集电极电流的关系

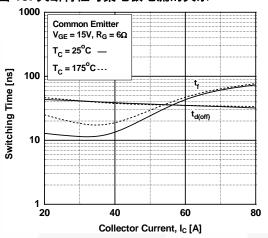


图 14. 开关损耗与集电极电流的关系

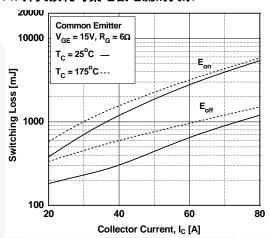


图 15. 负载电流与频率的关系

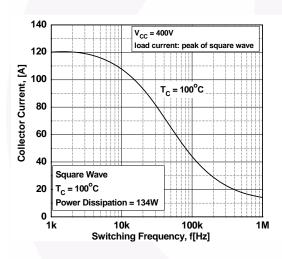


图 16. SOA 特性

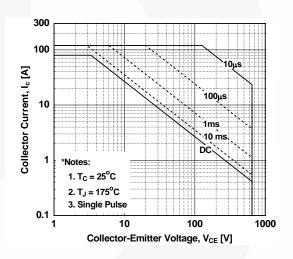


图 17. 正向特性

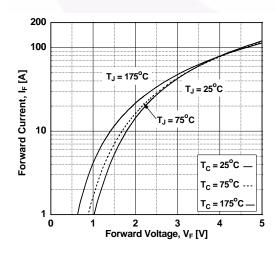


图 18. 反向恢复电流

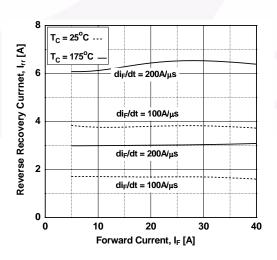


图 19. 反向恢复时间

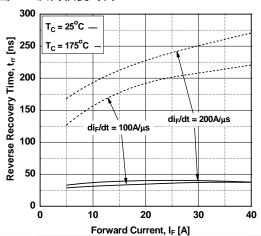


图 20. 存储电荷

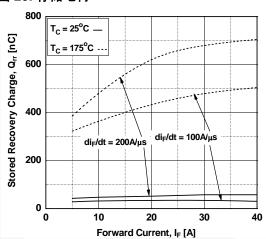


图 21. IGBT 瞬态热阻抗

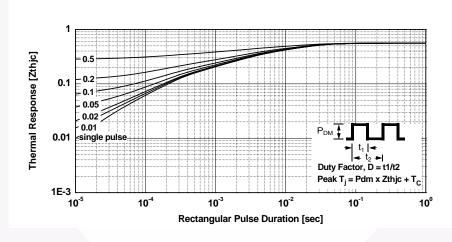
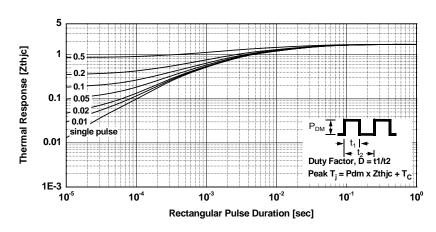
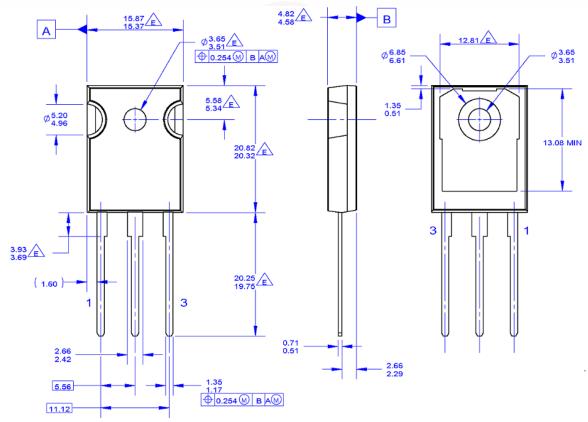


图 22. 二极管瞬态热阻抗



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  D. DRAWING CONFORMS TO ASME Y14.5 1994
- DOES NOT COMPLY JEDEC STANDARD VALUE F. DRAWING FILENAME: MKT-TO247G03\_REV01

#### 图 23. TO-247 3L - TO-247,模塑封装, 3 引脚, JEDEC AB 长引脚

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